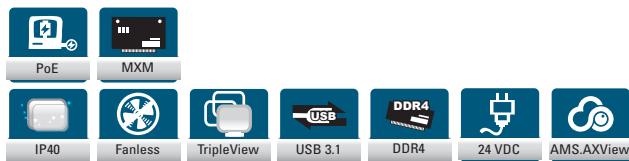


# eBOX671-521-FL

Fanless Embedded System with LGA1151 9th/8th Gen Intel® Core™ i7/i5/i3 & Celeron® Processors, 4-CH PoE and MXM 3.1 Type A

## Features

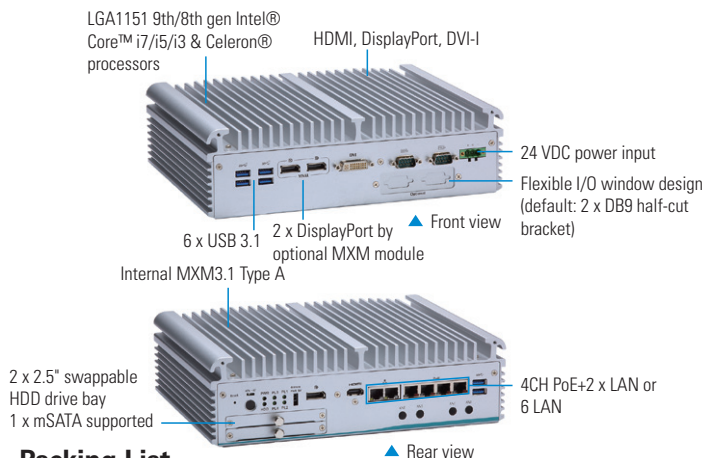
- 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® with Intel® Q370 chipset (Coffee Lake/Coffee Lake Refresh-S)
- 4-CH PoE (IEEE802.3at compliance)
- Dual swappable 2.5" SATA HDD drive bay with RAID 0 & 1
- Supports MXM 3.1 type A graphics module (optional)
- DVI-I, HDMI, and DisplayPort with triple-view supported
- AMS.AXView 3.0 intelligent remote monitoring software for IIoT



## Specifications

Standard Color	Silver
Construction	Aluminum extrusion and heavy-duty steel, IP40
CPU	LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processors (35W/65W)
System Memory	2 x 260-pin DDR4-2666 SO-DIMM, up to 64GB (ECC supported by Intel® C246 PCH)
Chipset	Intel® Q370/optional Intel® C246 PCH
BIOS	AMI
System I/O Outlet	2 x RS-232/422/485 2 x DisplayPort via optional MXM kit 1 x HDMI, 1 x DisplayPort, 1 x DVI-I 4 x Power over Ethernet (IEEE802.2at), up to 60W 2 x 10/100/1000 Mbps Ethernet (i210-IT & i219-LM) 4 x USB 3.1 Gen2, 2 x USB 3.1 Gen1 1 x Phoenix type VDC power input connector 1 x AT/ATX quick switch 1 x ATX power switch 1 x Reset switch 1 x Remote switch 1 x Flexible I/O window (Default : 2 x DB9 half-cut bracket) 4 x SMA-type antenna connector
Watchdog Timer	255 levels, 1 to 255 sec.
Storage	2 x 2.5" HDD drive bay (max. up 9.5 mm height) 1 x mSATA (enabled in BIOS setting)
Expansion Interface	2 x full-size PCI Express Mini Card slot (USB + PCIe signal) 2 x SIM slot 1 x internal MXM3.1 type A connector
TPM	TPM 2.0
System Indicator	1 x Green LED for system power-on 1 x Green LED for HDD active 4 x Green LED for programmable
Power Input	24 VDC
Operating Temperature	Without MXM module: -40°C to 60°C (-40°F to +140°F) (with W.T. DRAM & SSD, CPU TDP 35W) -40°C to 50°C (-40°F to +122°F) (with W.T. DRAM & SSD, CPU TDP 65W) With MXM module: -40°C to 50°C (-40°F to +122°F) (with W.T. DRAM & SSD & MXM kit, CPU TDP 35W)
Humidity	10% - 90%, non-condensing
Shock Vibration	IEC 60068-2-27 (w/ SSD: 50G@wall mount, half-sine, 11 ms duration)
Vibration Endurance	IEC 60068-2-64 (w/ SSD: 3Grms STD, random, 5 - 500 Hz, 1 hr/axis)
Dimensions	280 mm (11.02") (W) x 210 mm (8.26") (D) x 80.5 mm (3.16") (H)
Weight (net/gross)	4.8 kg (10.58 lb)/5.6 kg (12.34 lb)
Certifications	CE, FCC Class A
EOS Support	Win 10 IoT, Linux
Software Support	AMS.AXView 3.0

\* W.T.: Wide Temperature. All W.T. supported products have to be sorted by Axiomtek.



## Packing List

- 1 x Quick manual
- 1 x Driver CD
- 1 x Screw pack
- 4 x Pre-installed foot pad
- 1 x 3-pin terminal block connector
- 1 x Remote switch cable

## Power Protection

### DC Version

- OVP (over voltage protection)
- UVP (under voltage protection)
- OC (over current protection)
- SCP (short circuit protection)
- Reserve protection

## Ordering Information

### Standard

eBOX671-521-FL-DC-4PoE	Fanless embedded system with LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processor, Intel® Q370, DVI-I, HDMI, dual HDD, 4 PoE, 2 GbE LAN, 6 USB, 2 COM and 24 VDC
eBOX671-521-FL-DC-6GbE	Fanless embedded system with LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processor, Intel® Q370, DVI-I, HDMI, dual HDD, 6 GbE LAN, 6 USB, 2 COM and 24 VDC

### Optional

2.5" SATA HDD	80GB or above
2.5" SATA SSD	100GB or above
DDR4 SO-DIMM	4GB to 32GB
mSATA	64GB or above
8816K6718A0E	Wall mount kit
8816K6719A0E	DIN-rail kit
8816K6603A0E	Wi-Fi module
	3G/LTE module
	MXM 3.1 Type A module
50906D24000E	24V, 120W adapter
E392903102	AX92903 CANbus PCI Express Mini module
E392903103	AX92903 CAN module with CANOpen
E392902103	AX92902 LAN PCI Express Mini module
594066392140E	RS-232 cable, L=200 mm for COM3/4
E392904102	AX92904 DIO PCI Express Mini module

\* Specifications and certifications may vary based on different requirements.

## Dimensions

